

MX-COM, INC. MiXed Signal ICs

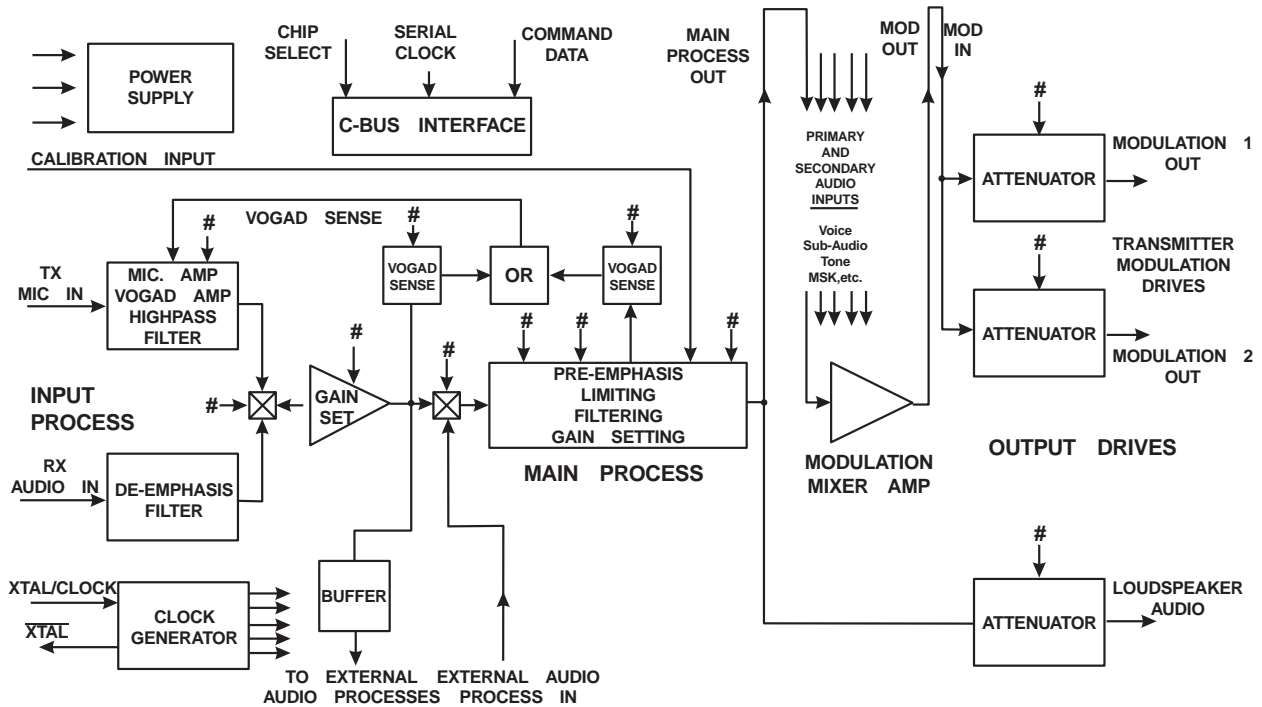
DATA BULLETIN

MX806A

Audio Processor

Features

- Half-Duplex Audio Processor
- Dynamic Control of Signal Levels
- Performs Signal Conditioning and Filtering requirements for both Transmit and Receive
- Three separate signal sections:
Input process
Main Process
Mixing and Output Drives
- Low Power Operation
- Member of DBS800 Family (C-BUS Compatible)



The MX806A LMR audio processor is intended too primarily to operate as the “Audio Terminal” or radio systems using the DBS800 Digitally Integrated Baseband Subsystem.

The MX806A half-duplex device has signal paths and level setting elements that are configured and adjusted by digital information sent from the radio microcontroller using C-BUS protocol. (C-BUS is the serial interface for all DBS 800 ICs.)

The Signal Path is divided into three sections: Input Process, Main process, and Mixing and Output Drives.

If selected, signal level stability and output accuracy of the MX806A is maintained by a voltage-controlled gain system using selectable signal-level detectors. Signal levels can be dynamically controlled to provide “dynamic compensation” for factors such as temperature drift, VCO non-linearity, etc.

The MX806A audio stages can be completely disabled – or the whole IC can be placed into powersave mode, leaving only clock and C-BUS circuitry active.

The MX806A may be used with a 5.0V power supply and is available in the following packages: 24-pin SOIC (MX806ADW), 24-pin PLCC (MX806ALH), and 24-pin PDIP (MX806AP).

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1 Block Diagram

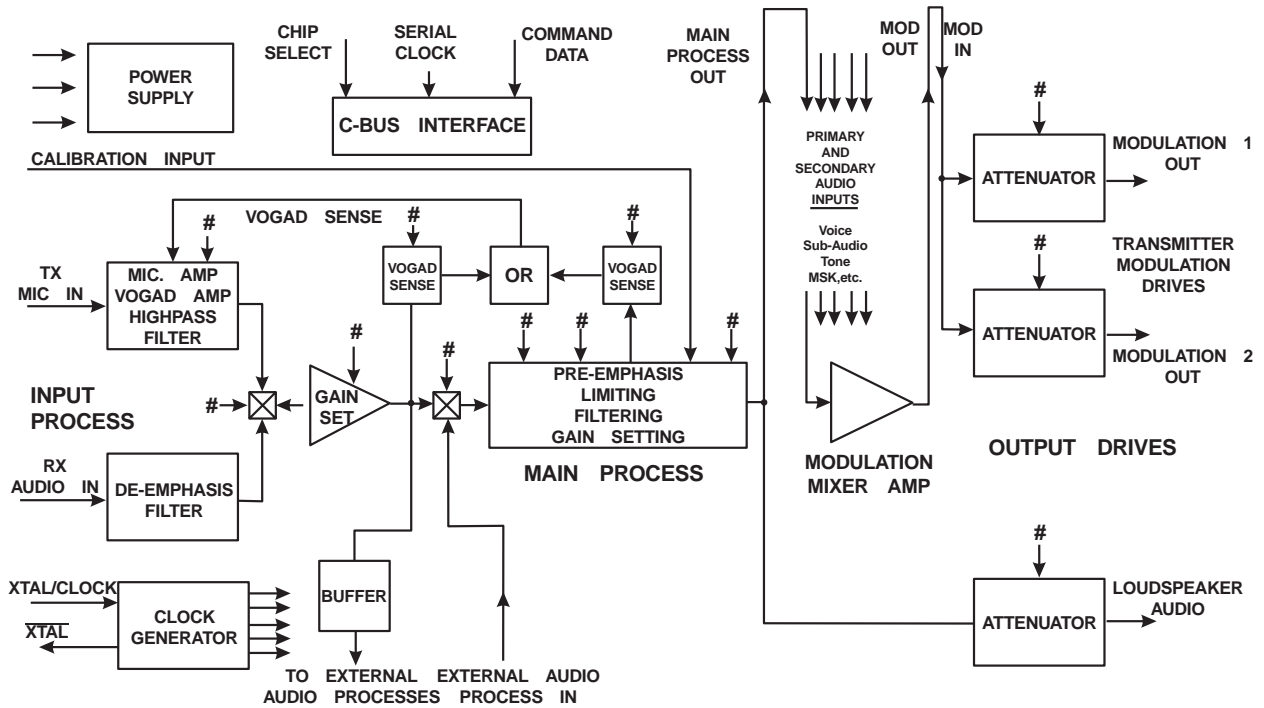


Figure 1: Block Diagram

2 Signal List

Pin	Signal	Description
1	$\overline{\text{Xtal}}$	The output of the 4.032MHz on-chip clock oscillator. External components are required at this output when a Xtal is used. See Figure 2.
2	Xtal/Clock	The input to the on-chip 4.032MHz clock oscillator inverter. A 4.032MHz Xtal or externally derived clock should be connected here. See Figure 2. This clock provides timing for on-chip elements, filters, etc.
3	Serial Clock	This is the 'C-BUS' serial Clock input. This clock, produced by the microcontroller, is used for transfer timing of commands and data to and from the MX805A. See Section 6 and Section 7.1.4.
4	Command Data	This is the 'C-BUS' serial data input from the microcontroller. Command Data is loaded to this device in 8-bit bytes, MSB (bit 7) first and LSB (bit 0) last, synchronized to the Serial Clock. The Command/Data instruction is acted upon at the end of loading the whole instruction. Command information is detailed in Table 3 through Table 7. See Section 6 and Section 7.1.4.
5	$\overline{\text{CS}}$	Chip Select. This is the 'C-BUS' data loading control function. This input is provided by the microcontroller. Command Data transfer sequences are initiated, completed or aborted by the $\overline{\text{CS}}$ signal. See Section 6 and Section 7.1.4.
6	VOGAD OUT	The error-voltage output of the selected VOGAD sensor. This output, with external attack and decay setting components, should be connected as in Figure 2 and Figure 3, to the VOGAD In pin.
7	RX Audio In	The audio input to the MX806A from the radio receiver's demodulator circuits. This input, which requires AC coupling with capacitor C12, is selected via a Control Command bit.
8	VOGAD In	The gain control signal from the selected VOGAD sensor (VOGAD Out) to the Input Process voltage-controlled amplifier. The required sensor is selected via a Mode Command. The choice of two sensors enables gain control from either the Input Process or an External Process. External attack and decay setting components should be applied as recommended. See Figure 2 and Figure 3.
9	V_{BIAS}	The output of the on-chip analog circuitry bias system, held internally at $V_{\text{DD}}/2$. This pin should be decoupled to V_{SS} by capacitor C10. See Figure 2.
10	Mic In (+)	The non-inverting input to the microphone Op-Amp. This input requires external components for Op-Amp gain/attenuation setting as shown in Figure 2.
11	Mic In (-)	The inverting input to the microphone Op-Amp. This input requires external components for Op-Amp gain/attenuation setting as shown in Figure 2.
12	V_{SS}	Negative Supply (GND)
13	Mic Out	The output of the Microphone Op-Amp, used with the Mic In (-) input to provide the required gain/attenuation using external components as shown in Figure 2. The external components shown are to assist in the use of this amplifier with either inverting or non-inverting inputs. During Powersave (Volume Command this output is placed at V_{SS} .)
14	Processed Audio In	The input to the device from such external audio processed as Voice Store and Retrieve or Frequency Domain Scrambling. This input, which requires AC Coupling with capacitor C13, is selected by a Mode Command bit.
15	External Audio Process	The buffered output of the Input Processing Stage. Its purpose is to further external audio processing stages prior to re-introduction at the Processed Audio In Pin.
16	Calibration Input	A unique audio input to be used for dynamic balancing of the modulator drives for measuring Deviation Limiter levels. A CUE (beep) input from the MX803 Audio Tone Processor can be entered on this line. This audio input must be externally biased. It is selected via a Mode Command bit.
17	Main Process Out	The output of the Main Process stage. This output should be mixed with any additional system audio inputs (Audio, Sub-Audio Signaling, MSK) in the on-chip Modulation Summing Amplifier. External components shown in Figure 2 should be used as required.

Pin	Signal	Description
18	Sum In	The input and output terminals of the on-chip Modulation Summing Amplifier. External components are required for input signals and gain/attenuation setting as shown in Figure 2. For single-signal, no gain requirements, Main Process Out may be linked directly to Modulation In.
19	Sum Out	
20	Modulation In	The final, composite modulating signal to VCO (Mod 1) and Reference (Mod 2) Output Drives
21	Audio Output	The processed audio signal output intended as a received audio (volume) output. Though normally used in the RX mode, operation in TX is permitted. The output level of this attenuator is controlled via a Volume Set command. During Powersave this output is placed at V_{SS} .
22	Modulation 1 Drive	The drive to the radio modulator Voltage Controlled Oscillator (VCO) from the composite audio summing stage.
23	Modulation 2 Drive	The drive to the radio modulator Reference Oscillator from the composite audio summing stage. Note: These VCO output attenuators are individually adjustable using the Modulator Level command. During Powersave these outputs are placed at V_{SS} .
24	V_{DD}	Positive Supply. A single 5.0V regulated supply is required. Levels and voltages within this Audio Processor are dependent upon this supply.

Table 1: Signal List

3 External Components

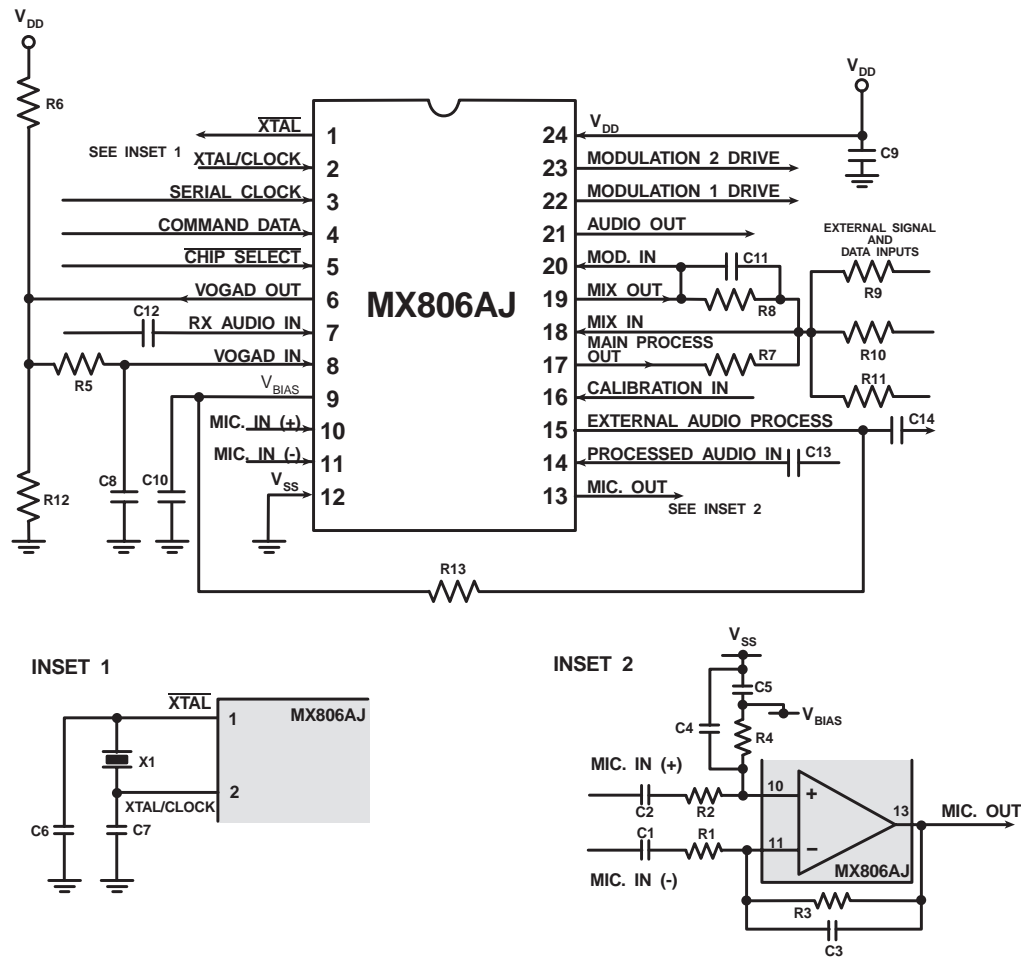


Figure 2: Recommended External Components

Component	Notes	Value	Tolerance
R1		10kΩ	±10%
R2		10kΩ	±10%
R3		20kΩ	±10%
R4		20kΩ	±10%
R5		10kΩ	±10%
R6		2.2MΩ	±10%
R7		100kΩ	±10%
R8		100kΩ	±10%
R9		100kΩ	±10%
R10		100kΩ	±10%
R11		100kΩ	±10%
R12		2.2MΩ	±10%
R13		470kΩ	±10%
C1		.47μF	±20%

Component	Notes	Value	Tolerance
C2		.47μF	±20%
C3		270pF	±20%
C4		270pF	±20%
C5		0.1μF	±20%
C6		33pF	±20%
C7		5-65pF	±20%
C8		1.0μF	±20%
C9		1.0μF	±20%
C10		1.0μF	±20%
C11		22pF	±20%
C12		0.1μF	±20%
C13		0.01μF	±20%
C14		0.01μF	±20%
X1		4.00MHz	

Table 2: Recommended External Components

Recommended External Component Notes:

1. Input Op-Amp gain/attenuation components (voltage gain = 6.0dB) are shown in Inset 1 is a differential configuration to demonstrate the versatility of this input. Components for a single (+ or -) input may be used.
2. Resistor values R7 to R11 (summation components) are dependent upon application and configuration requirements.
3. Xtal circuit capacitors C6 (CD) and C7 (CG) shown in Inset 2 are recommended in accordance with MX-COM's Crystal Oscillator Application Note. Circuit drive and drain resistors are incorporated on-chip. Operation of any MX-COM IC without a Xtal clock input may cause device damage. To minimize damage in the event of a Xtal/drive failure, you should install a current limiting device (resistor or fast-reaction fuse) on the power-input (V_{DD}).

4 General Description

The MX806A LMR audio processor is intended too primarily to operate as the "Audio Terminal" or radio systems using the DBS800 Digitally Integrated Baseband Subsystem.

The MX806A half-duplex device has signal paths and level setting elements that are configured and adjusted by digital information sent from the radio microcontroller using C-BUS protocol. (C-BUS is the serial interface for all DBS 800 ICs.)

4.1 Signal Path

The Signal path is divided into three sections:

Input Process: This stage has selectable TX/RX paths. Transmits voice signals pass through microphone pre-amplifier, voltage controlled gain (VOGAD) and highpass filter stages. Received audio is de-emphasized. This initial audio, after line-in gain adjustment, may be switched to external audio processes (such as scrambling) or to the internal Main Process stages.

Main Process: Conditioning for the input or external process signals is completed in this stage. It is comprised of pre-emphasis, high and lowpass switched capacitor filters and a deviation limiter.

Mixing and Output Drives: Main audio for transmission is mix with signaling and data from external sources (other DBS 800 ICs) to provide the composite signal for the digitally adjustable transmitter modulation drives. Received audio level is adjusted for output to loudspeaker circuitry.

If selected, signal level stability and output accuracy of the MX806A is maintained by a voltage-controlled gain system using selectable signal-level detectors. Signal levels can be dynamically controlled to provide "dynamic compensation" for factors such as temperature drift, VCO non-linearity, etc.

The MX806A audio stages can be completely disabled – or the whole IC can be placed into powersave mode, leaving only clock and C-BUS circuitry active.

4.2 VOGAD

The overall Gain Control system of the MX806A consists of 2 selectable signal peak detectors whose output is fed via external integrating components to adjust the gain of the Voltage Controlled Amplifier positioned in the TX Input Process Path. The transmit input signals is presented to Peak Detector 1 or 2. The Peak Detectors are enabled individually by a Mode Command. When the input signal exceeds the peak - to - peak threshold of the detector, a 5-volt level is produced at the VOGAD Out pin. This level remains for as long as the signal exceeds the threshold. The integrated level to the VOGAD In pin causes the Voltage Controlled Amplifier gain to be reduced. As can be seen from Figure 3 and Figure 5, Peak Detector 1 allows control of the audio level to the external audio process and Peak Detector 2 allows control of transmit deviation levels.

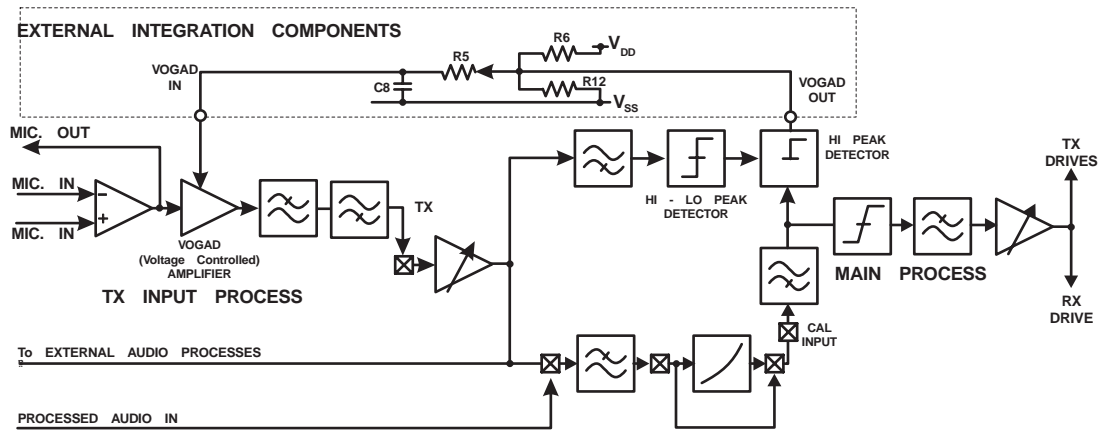


Figure 3: VOGAD Sensors and Timing Components (from Figure 5)

VOGAD attack and decay times are set using the external components shown in Figure 2 and Figure 3. They are calculated as described below.

4.2.1 VOGAD Components Calculations – Figure 2 and Figure 5

Provided $R5 \gg 1.0k$ and $R6 = R12 \gg R5$

Then

$$\text{Attack Time } (T_A) = R5 \times C8$$

$$\text{Decay Time } (T_D) = \frac{R6 \times C8}{2}$$

4.3 Calibration Methods

To effectively null all internal IC tolerance, the following initial calibration routine is suggested.

4.3.1 TX Calibration: From Mic. In to Modulator Drives Out

Disable Peak Detectors (Mode Command)

Set Transmitter Drives to 0dB (Mod. Levels Set)

Pre-emphasis may be employed as required (Control Command)

Set Input Level Amp to 0dB Control Command)

1. Mic. In = 250mVRMS at 1kHz. Set Process Gain Amp for output of 1440mV_{P-P} (100% deviation).
2. With Process Gain Amp set as 1 and with Mic. In = 25mV_{RMS} at 1kHz, set the Input Level Amp for an output level of 308mV_{RMS} (60% deviation)

4.3.2 RX Calibration: From RX Audio In to Audio Out

Set Audio Output Drive In to Audio Out

Leave Process Gain Amp set as 1 (See Section 4.3.1)

3. With and RX Audio In level of between 154mV_{RMS} and 308mV_{RMS} (See Section 7) at 1kHz, set the Input Level Amp for and output level of 308mV_{RMS}.

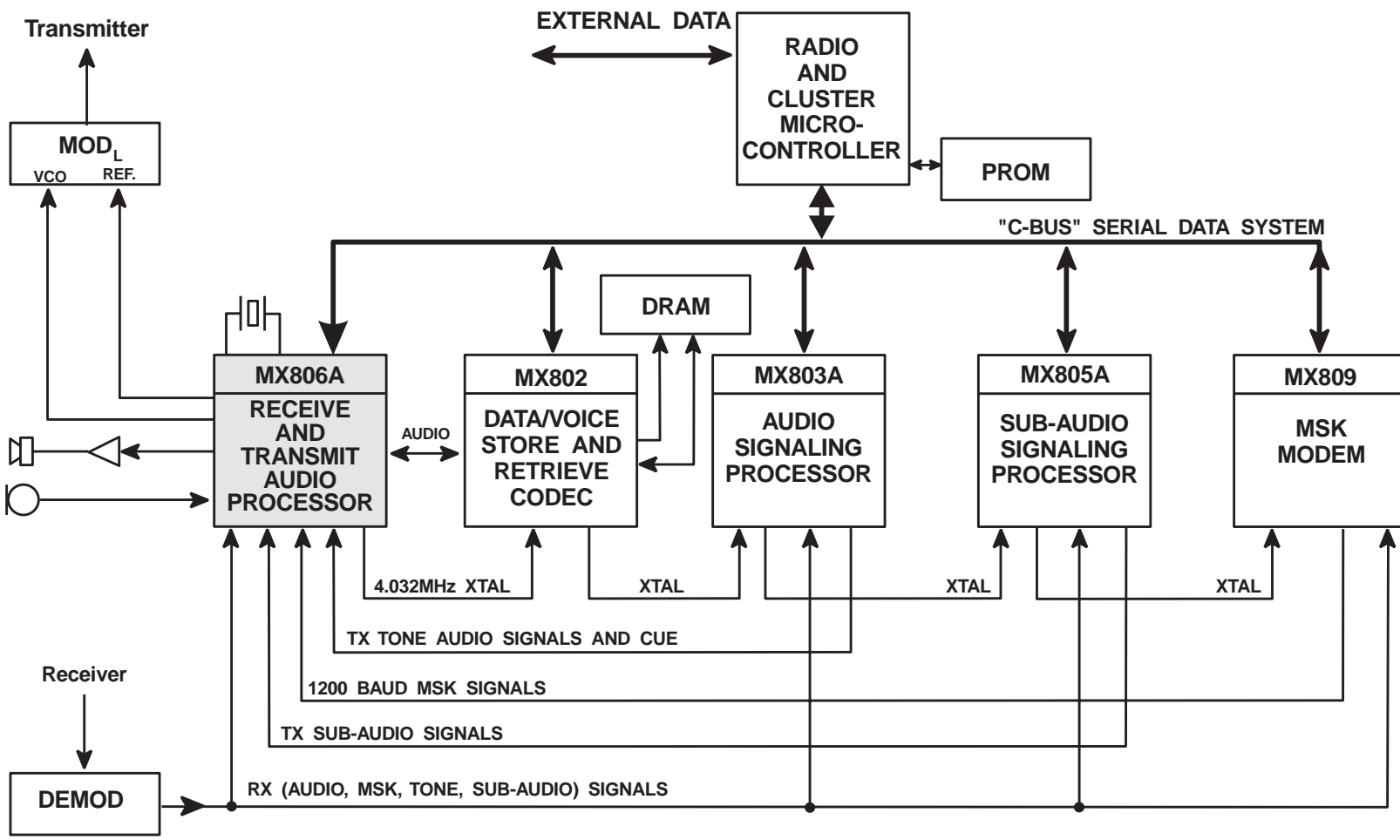
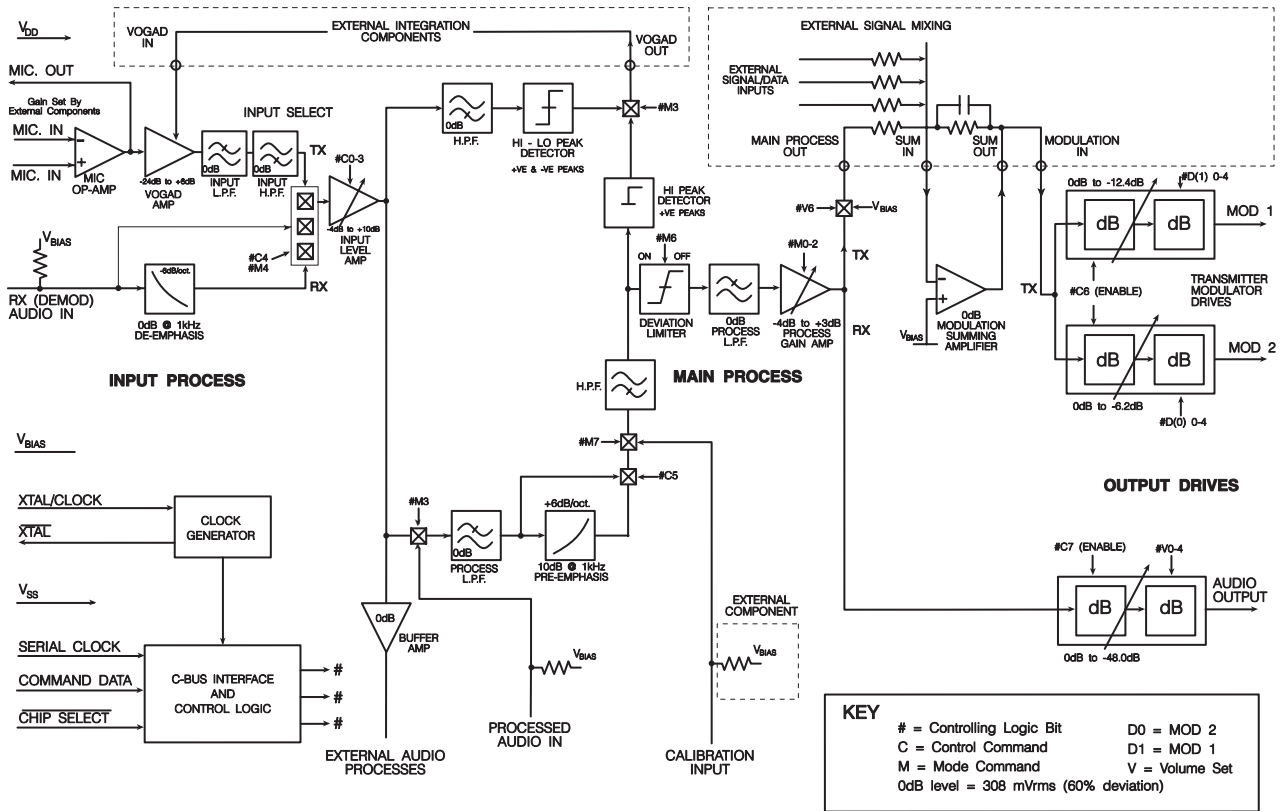


Figure 4: MX806A Interfaced with Other DBS 800 Elements

Figure 4 - MX806A Interfaced with Other DBS800 Elements



MX806A - LMR Audio Processor Explanatory Block Diagram

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Figure 5: LMR Audio Processor Explanatory Block Diagram

5 Controlling Protocol

Control of the functions and levels within the MX806A LMR Audio processor is by a group of Address/Commands and appended data instructions from the system microcontroller. The use of these instructions is detailed in the following paragraphs and tables.

Command Assignment	HEX	Address/Command Binary		Command Data	Table
		MSB	LSB		
General Reset	01	00000001			
Control Command	10	00010000		+ 1 byte	2
Mode Command	11	00010001		+ 1 byte	3
Mod. Levels Set	12	00010010		+ 2 bytes	4
Volume Set	13	00010011		+ 1 byte	5

Table 3: C-BUS Address/Commands

In "C-BUS" protocol the MX806A is allocated Address/Command values 10H and 13H. C-BUS Command Mode, Modulation and Volume assignments, and data requirements are given in Table 3 and illustrated in Figure 5.

Commands and Data are only to be loaded in the group configurations detailed since the "C-BUS" interface recognizes the first byte after Chip Select (logic "0") as an Address/Command.

Function or Level control data, which is detailed in Table 4, Table 5, Table 6, and Table 7, is acted upon at the end of the loaded instruction

Upon power-up the value of the “bits” in this device will be random (either “0” or “1”). A General Reset Command (01H) is required. This command is provided to “reset” all devices on the Command “Data line and has the following effect on the MX806A:

Control Address Command	Loaded as 00 _H
Mode Address Command	Loaded as 00 _H
Volume Set	Loaded as 00 _H

5.1.1 Control Command – (Preceded by A/C 10_H)

Settings				Control Bits
MSB				
7				Audio Output (RX)
0				Disabled
1				Enabled
6				Modulation Drives
0				Disabled
1				Enabled
5				Pre-Emphasis
0				Bypass
1				Enabled
4				Input Select
0				RX In
1				Mic. In
3	2	1	0	Input Level Set
0	0	0	0	Input Amp Disabled
0	0	0	1	-4.0dB
0	0	1	0	-3.0dB
0	0	1	1	-2.0dB
0	1	0	0	-1.0dB
0	1	0	1	0dB
0	1	1	0	1.0dB
0	1	1	1	2.0dB
1	0	0	0	3.0dB
1	0	0	1	4.0dB
1	0	1	0	5.0dB
1	0	1	1	6.0dB
1	1	0	0	7.0dB
1	1	0	1	8.0dB
1	1	1	0	9.0dB
1	1	1	1	10.0dB

Table 4: Control Commands

5.1.2 Mode Command – (Preceded by A/C 11_H)

Setting			Mode Bits
MSB			
7			Drive Source
0			Signals
1			Calibration
6			Deviation Limiter
0			Disabled
1			Enabled
5			VOGAD
0			Disabled
1			Enabled
4			De-Emphasis
0			Enabled
1			Bypassed
3			Signal Select
0			Internal
1			External
2	1	0	Process Gain Set
0	0	0	-4.0dB
0	0	1	-3.0dB
0	1	0	-2.0dB
0	1	1	-1.0dB
1	0	0	0dB
1	0	1	1.0dB
1	1	0	2.0dB
1	1	1	3.0dB

Table 5: Mode Commands

5.1.3 Modulator Levels – (Preceded by A/C 12_H)

Setting					Modulator Drives
Byte 1					First byte for transmission
MSB					
7	6	5			
0	0	0			Must be "0"
4	3	2	1	0	VCO Drive Attenuation
0	0	0	0	0	12.4dB
0	0	0	0	1	12.0dB
0	0	0	1	0	11.6dB
0	0	0	1	1	11.2dB
0	0	1	0	0	10.8dB
0	0	1	0	1	10.4dB
0	0	1	1	0	10.0dB
0	0	1	1	1	9.6dB
0	1	0	0	0	9.2dB
0	1	0	0	1	8.8dB
0	1	0	1	0	8.4dB
0	1	0	1	1	8.0dB
0	1	1	0	0	7.6dB
0	1	1	0	1	7.2dB
0	1	1	1	0	6.8dB
0	1	1	1	1	6.4dB
1	0	0	0	0	6.0dB
1	0	0	0	1	5.6dB
1	0	0	1	0	5.2dB
1	0	0	1	1	4.8dB
1	0	1	0	0	4.4dB
1	0	1	0	1	4.0dB
1	0	1	1	0	3.6dB
1	0	1	1	1	3.2dB
1	1	0	0	0	2.8dB
1	1	0	0	1	2.4dB
1	1	0	1	0	2.0dB
1	1	0	1	1	1.6dB
1	1	1	0	0	1.2dB
1	1	1	0	1	0.8dB
1	1	1	1	0	0.4dB
1	1	1	1	1	0dB

Setting					Modulator Drives
Byte 0					Last byte for transmission
MSB					
7	6	5			
0	0	0			Must be "0"
4	3	2	1	0	VCO Drive Attenuation
0	0	0	0	0	6.2dB
0	0	0	0	1	6.0dB
0	0	0	1	0	5.8dB
0	0	0	1	1	5.6dB
0	0	1	0	0	5.4dB
0	0	1	0	1	5.2dB
0	0	1	1	0	5.0dB
0	0	1	1	1	4.8dB
0	1	0	0	0	4.6dB
0	1	0	0	1	4.4dB
0	1	0	1	0	4.2dB
0	1	0	1	1	4.0dB
0	1	1	0	0	3.8dB
0	1	1	0	1	3.6dB
0	1	1	1	0	3.4dB
0	1	1	1	1	3.2dB
1	0	0	0	0	3.0dB
1	0	0	0	1	2.8dB
1	0	0	1	0	2.6dB
1	0	0	1	1	2.4dB
1	0	1	0	0	2.2dB
1	0	1	0	1	2.0dB
1	0	1	1	0	1.8dB
1	0	1	1	1	1.6dB
1	1	0	0	0	1.4dB
1	1	0	0	1	1.2dB
1	1	0	1	0	1.0dB
1	1	0	1	1	0.8dB
1	1	1	0	0	0.6dB
1	1	1	0	1	0.4dB
1	1	1	1	0	0.2dB
1	1	1	1	1	0dB

Table 6: Modulator Drive Levels

5.1.4 Volume Set – (Preceded by A/C 13_H)

Setting					Volume Set
MSB					
7		5			Main Process Out
0		0			Enabled
0		1			Biased
5					Powersave
0					Chip Enabled
1					Powersaved
4	3	2	1	0	VCO Drive Attenuation
0	0	0	0	0	OFF
0	0	0	0	1	48.0dB
0	0	0	1	0	46.4dB
0	0	0	1	1	44.8dB
0	0	1	0	0	43.2dB
0	0	1	0	1	41.6dB
0	0	1	1	0	40.0dB
0	0	1	1	1	38.4dB
0	1	0	0	0	36.8dB
0	1	0	0	1	35.2dB
0	1	0	1	0	33.6dB
0	1	0	1	1	32.0dB
0	1	1	0	0	30.4dB
0	1	1	0	1	28.8dB
0	1	1	1	0	27.2dB
0	1	1	1	1	25.6dB
1	0	0	0	0	24.0dB
1	0	0	0	1	22.4dB
1	0	0	1	0	20.8dB
1	0	0	1	1	19.2dB
1	0	1	0	0	17.6dB
1	0	1	0	1	16.0dB
1	0	1	1	0	14.4dB
1	0	1	1	1	12.8dB
1	1	0	0	0	11.2dB
1	1	0	0	1	9.6dB
1	1	0	1	0	8.0dB
1	1	0	1	1	6.4dB
1	1	1	0	0	4.8dB
1	1	1	0	1	3.2dB
1	1	1	1	0	1.6dB
1	1	1	1	1	0dB

Table 7: Volume Set

Notes:

1. Command Loading: Address/Commands and data bytes must be loaded in accordance with the information given in Figure 7.
2. The powersave function is enabled by bit 5 of the Volume Set Command (Table 7). During Powersave all internal elements except the clock Generator and "C-BUS" interface are off. The Mic Op-Amp and output Drive stage outputs are connected to V_{SS}.
3. Modulator Drives are controlled separately, but the whole two-byte modulator Drive command must be loaded for each requirement adjustment.
4. Chip Select must be held at a logic "1" for the period "t_{CSOFF}" between transactions.

6 Application Notes

To assist in rapid setting, this quick-reference list should be used with Figure 5.

Control	A/C = 10_H
7	Audio Out (RX) Enable
6	Modulator Drive Enable
5	Pre-Emphasis Select
4	Input Select (RX/TX)
3-0	Input Level Set (-4dB to 10dB)
Mode	A/C = 11_H
7	Drive Source
6	Derivation Limiter Enable
5	VOGAD Enable
4	De-emphasis Enable
3	Signal Select
2-0	Process Gain Set
Modulator Levels	A/C = 12_H
Byte 1	
7-5	"0"
4-0	Mod 1 Attenuation (0 to 12.4dB)
Byte 2	
7-5	"0"
4-0	Mod 2 Attenuation (0 to 6.2dB)
Volume Set	A/C = 13_H
7-6	"0"
5	Powersave
4-0	Volume Set Attenuation (0 to 48dB)

Table 8: Quick Reference List

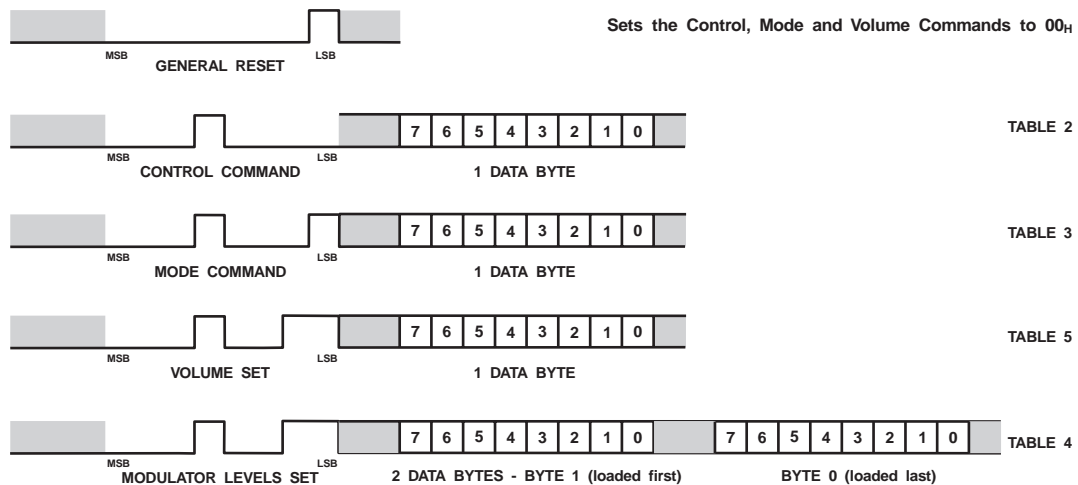


Figure 6: Examples of Command Data Configurations

7 Performance Specifications

7.1 Electrical Specifications

7.1.1 Absolute Maximum Limits

Exceeding these maximum ratings can result in damage to the device.

General	Notes	Min.	Typ.	Max.	Units
Supply ($V_{DD}-V_{SS}$)		-0.3		7.0	V
Voltage on any pin to V_{SS}		-0.3		$V_{DD} + 0.3$	V
Current					
V_{DD}		-30		30	mA
V_{SS}		-30		30	mA
Any other pin		-20		20	mA
P / DW / LH Packages					
Total allowable Power dissipation at $T_{AMB} = 25^{\circ}\text{C}$				800	mW
Derating above 25°C			10		mW/ $^{\circ}\text{C}$ above 25°C
Operating Temperature		-40		85	$^{\circ}\text{C}$
Storage Temperature		-55		125	$^{\circ}\text{C}$

Table 9: Absolute Maximum Ratings

7.1.2 Operating Limits

Correct Operation of the device outside these limits is not implied.

	Notes	Min.	Typ.	Max.	Units
Supply ($V_{DD}-V_{SS}$)		4.5	5.0	5.5	V
Operating Temperature		-40		85	$^{\circ}\text{C}$
Xtal Frequency			4.0		MHz

Table 10: Operating Limits

7.1.3 Operating Characteristics

For the following conditions unless otherwise specified.

$V_{DD} = 5.0V @ T_{AMB} = 25^{\circ}C$

Xtal/Clock Frequency = 4.0MHz, Audio Level 0dB ref. = 308mV_{RMS} @ 1kHz (60% deviation, FM)

	Notes	Min.	Typ.	Max.	Units
Static Values					
Supply Current					
All Elements Enabled			8.0	15.0	mA
Maximum Powersave			0.7	1.5	mA
"C-BUS" Interface					
Input Logic "1"		3.5			V
Input Logic "0"				1.5	V
Input Current		-1.0		1.0	μA
Input Capacitance				7.5	pF
Overall Performance					
Microphone Input Level	1, 2		25		mV _{RMS}
Discriminator Input Level	2, 3	154		308	mV _{RMS}
Output Drive Level					
60% Deviation	2, 4	291	308	326	mV _{RMS}
100% Deviation	2, 4, 5		1440		MV _{P-P}
Passband	6	297		3000	Hz
Passband Ripple	7	-2		0.5	dB
Stopband Attenuation	6, 8				
@ 150Hz		10	12		dB
@ 3400Hz			2		dB
@ 6000Hz		30	36		dB
@ 8000Hz to 20,000Hz			60		dB
Signal Path Noise					
TX			-50		dBp
TX	9		-45		dB
RX			-60		dB
RX	9		-55		dB
Total Harmonic Distortion					
RX or TX, 60% Deviation			1.0		%
Circuit Elements – Figure 5					
Mic. Amp or Mod. Summation Amp					
Open Loop Gain			50.0		dB
Bandwidth		20.0			kHz
Input Impedance		10.0			MΩ
Output Impedance					
Open Loop			6.0		kΩ
Closed Loop			600		Ω
De-emphasis					
Slope			-6.0		dB/octave
Gain			0		dB
Input Impedance			1		MΩ

	Notes	Min.	Typ.	Max.	Units
Voltage Controlled Gain Amp (VOGAD)					
Gain					
Non-Compression	2		6.0		dB
Full-Compression			-24		dB
Input Impedance		10.0			M Ω
VOGAD Peak Detectors					
Output Impedance					
Logic "1" (Compress)			1		k Ω
Logic "0"			10		M Ω
Hi/Lo Peak Detector Threshold	10		1300		mV _{P-P}
Hi Peak Detector Threshold	10		650		mV + ve pk
Input (Low + Highpass) Filter					
Gain @ 1.0kHz		-1.0		1.0	dB
Input Level Amp					
Gain Range			0		dB
Overall Tolerance		-1.0		1.0	dB
Step Size		0.75	1.0	1.25	dB
External Audio Buffer					
Gain		-0.1	0	0.1	dB
Pre-emphasis (Main Process and VOGAD)					
Slope			6.0		dB/octave
Gain @ 1.0kHz			10.0		dB
Process Highpass Filter					
Gain @ 1.0kHz		-0.1	0	0.1	dB
Deviation Limiter					
Threshold		708	1300	1413	mV _{RMS}
Gain		-0.5		0.5	dB
Process Lowpass Filter					
Gain @ 1.0kHz		-0.1	0	0.1	dB
Process Gain Amp					
Gain Range		-4.0		3.0	dB
Overall Tolerance		-0.5		0.5	dB
Step Size		0.75	1.0	1.25	dB
Output Impedance			600		Ω
Transmitter Modulator Drives					
Input Impedance			15.0		k Ω
Mod. 1 Attenuator					
Attenuation Range		0		12.4	dB
Overall Tolerance		-1		1	dB
Step Size		0.2	0.4	0.6	dB
Output Impedance			600		Ω
Mod. 2 Attenuator					
Attenuation Range		0		6.2	dB
Overall Tolerance		-0.5		0.5	dB
Step Size		0.1	0.2	0.3	dB
Output Impedance			600		Ω

	Notes	Min.	Typ.	Max.	Units
Audio Output Attenuator					
Attenuation Range		0		48.0	dB
Overall Tolerance		-1.0		1.0	dB
Step Size		1.1	1.6	2.1	dB
Output Impedance			600		Ω
Miscellaneous Impedances					
Processed Audio Input			500		$k\Omega$
Calibration Input			500		$k\Omega$
External Process Out			100		Ω
RX with De-emphasis Bypass			25.0		$k\Omega$

Table 11: Operating Characteristics

Operating Characteristics Notes:

1. Producing an output of 0dB with the Mic. Op-Amp set to 6dB (as shown in Figure 2) and the Modulator Drives set to 0dB.
2. With Output Drives set to 0dB and the system calibrated as described in the Application Notes.
3. Input level range for 0dB output, by adjustment of the Input Level Amp.
4. It is recommended that these output levels will produce 60% or 100% deviation in the transmitter.
5. With the microphone input level 20dB above the level required to produce 0dB at the Output Drives.
6. Between Microphone or RX inputs to Modulator or Audio Outputs.
7. Deviation from the ideal overall response including the pre- or de-emphasis slope.
8. Excluding the effect of pre- or de-emphasis slope.
9. In a 30kHz bandwidth.
10. Using pre-emphasis in the TX path.

7.1.4 Timing

Timing Parameters for two-way communications between the μC and the MX805A on the C-BUS are shown in Table 12.

C-BUS Timing		Min.	Typ.	Max.	Units
t_{CSE}	Chip Select Low to First Serial Clock Rising Edge	2.0			μs
t_{CHS}	Last Serial Clock Rising Edge to Chip Select High	4.0			μs
t_{CSOFF}	Chip Select High time between transactions	2.0			μs
t_{NXT}	Inter-Byte Time	4.0			μs
t_{CK}	Serial Clock Period	2.0			μs

Table 12: Timing Information

Notes:

1. Command Data is transmitted to the peripheral MSB (bit 7) first, LSB (bit 0) last. Reply Data is read from the MX805A MXB (bit 7) first, LSB (bit 0) last.
2. Data is clocked into the MX805A and into the microcontroller on the rising Serial Clock edge.
3. Loaded data instructions are acted upon at the end of each individual, loaded byte.
4. To allow for differing microcontroller serial interface formats, the MX806A will work with either polarity Serial Clock pulses.

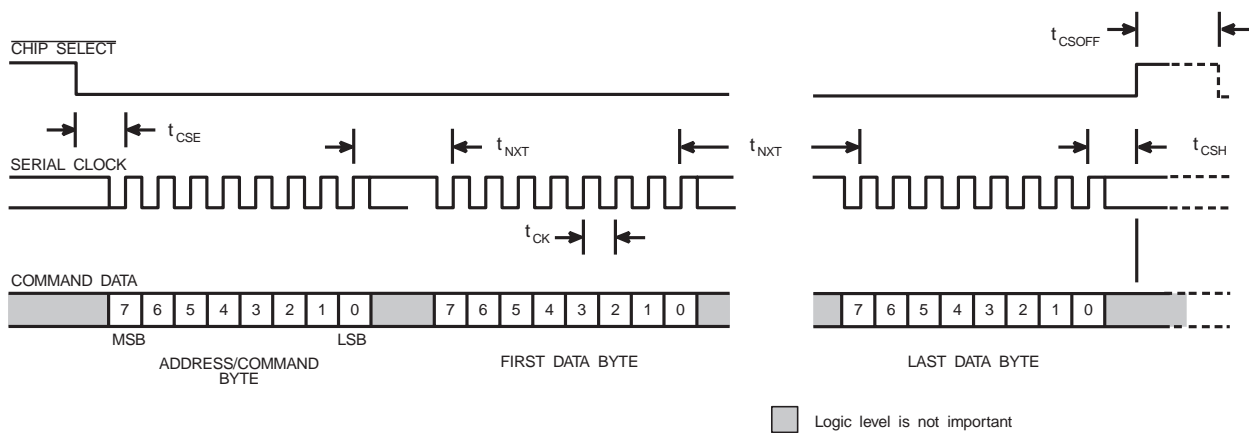


Figure 7: C-BUS Timing Information

7.2 Packages

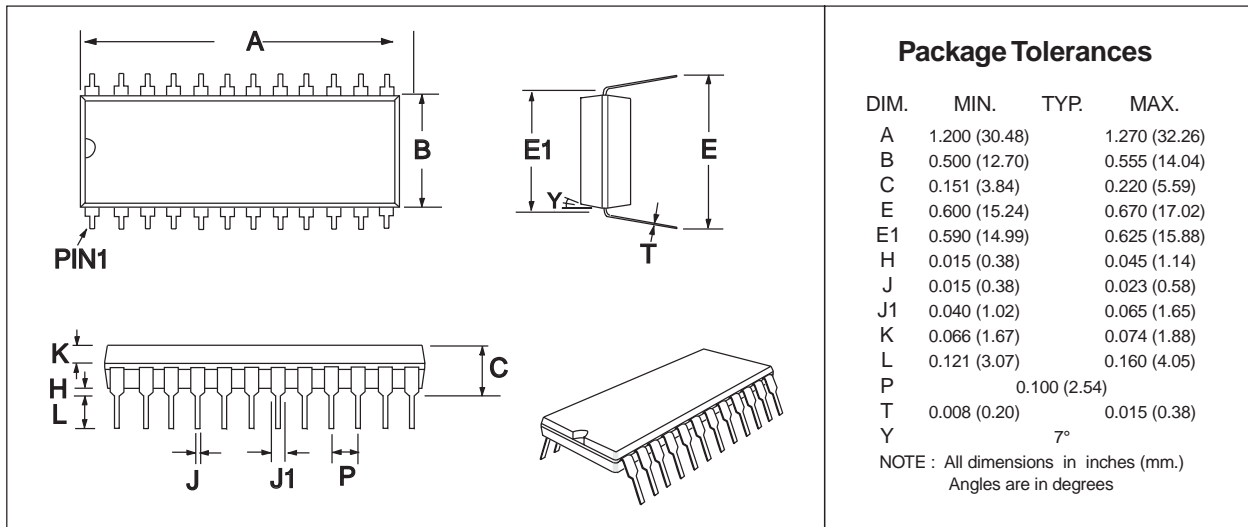


Figure 8: 24-pin PDIP Mechanical Outline: *Order as part no. MX806AP*

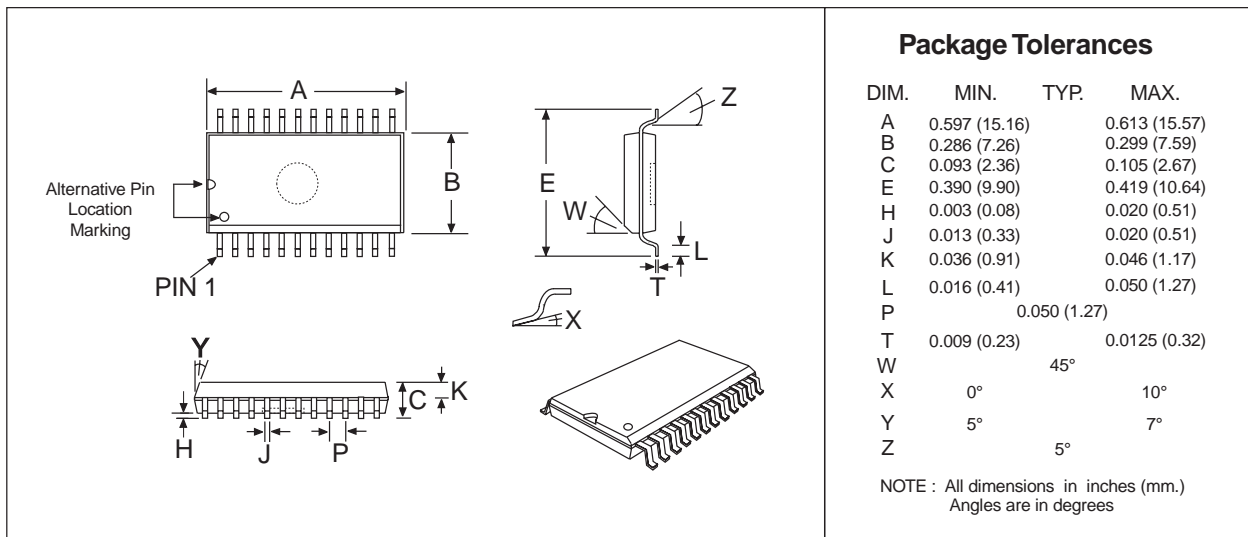


Figure 9: 24-pin SOIC Mechanical Outline: *Order as part no. MX806ADW*

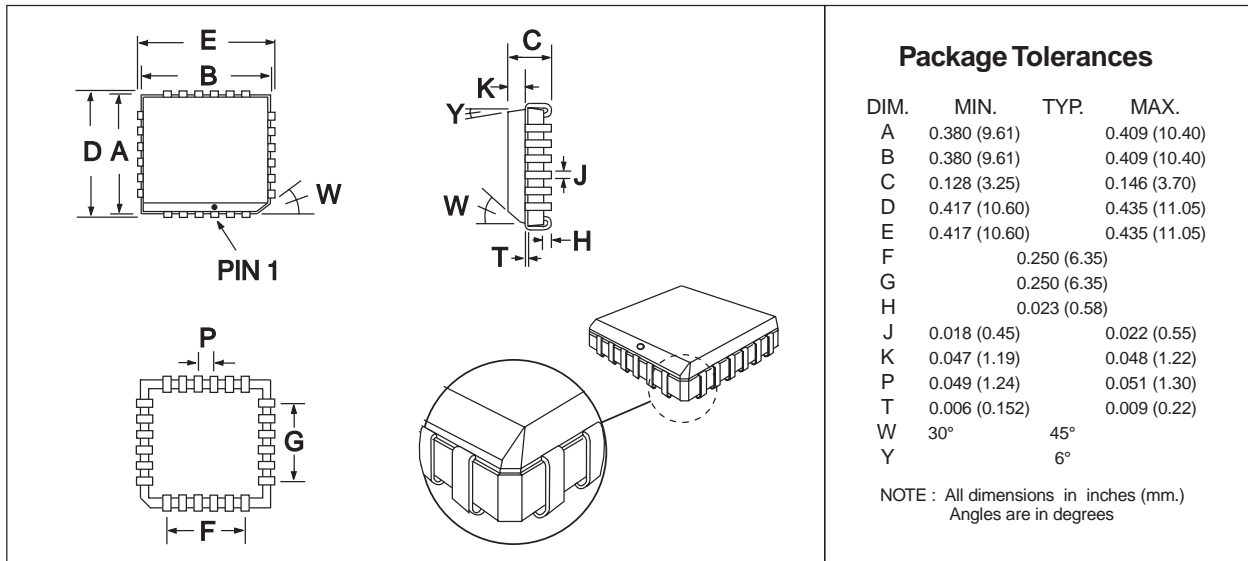


Figure 10: 24-pin PLCC Mechanical Outline: *Order as part no. MX806ALH*



CML Microcircuits

COMMUNICATION SEMICONDUCTORS

CML Product Data

In the process of creating a more global image, the three standard product semiconductor companies of CML Microsystems Plc (*Consumer Microcircuits Limited (UK)*, *MX-COM, Inc (USA)* and *CML Microcircuits (Singapore) Pte Ltd*) have undergone name changes and, whilst maintaining their separate new names (*CML Microcircuits (UK) Ltd*, *CML Microcircuits (USA) Inc* and *CML Microcircuits (Singapore) Pte Ltd*), now operate under the single title **CML Microcircuits**.

These companies are all 100% owned operating companies of the CML Microsystems Plc Group and these changes are purely changes of name and do not change any underlying legal entities and hence will have no effect on any agreements or contacts currently in force.

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Until the latter part of 1996, the differentiator between products manufactured and sold from MXCOM, Inc. and Consumer Microcircuits Limited were denoted by the prefixes MX and FX respectively. These products use the same silicon etc. and today still carry the same prefixes. In the latter part of 1996, both companies adopted the common prefix: CMX.

This notification is relevant product information to which it is attached.

CML Microcircuits (USA) [formerly MX-COM, Inc.] Product Textual Marking

On CML Microcircuits (USA) products, the '**MX-COM**' textual logo is being replaced by a '**CML**' textual logo.

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